Abstract of the Disclosure

Apparatus and a concomitant method for cooling a workpiece comprising a thermally conductive pedestal having a support surface upon which is affixed an electrostatic chuck for supporting and electrostatically retaining the workpiece. The electrostatic chuck retains a wafer in close contact with the pedestal such that heat conduction from the wafer to the pedestal is substantially improved over the prior art. Such close contact between the wafer and the chuck facilitates the use of a backside cooling technique to further promote the conduction of heat to the chuck.

This Sheet Has Been Replaced



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